

We claim:

1. A semiconductor device comprising:
a gate oxide layer on a semiconductor
5 substrate;
a conductive layer on the gate oxide layer;
and
a metal oxide layer at an interface between
the gate oxide layer and the conductive layer.

10 2. The semiconductor device according to claim 1,
wherein the gate oxide layer is a silicon oxide layer.

15 3. The semiconductor device according to claim 1,
wherein the gate oxide layer has a thickness of 10 to
100Å.

20 4. The semiconductor device according to claim 1,
wherein the conductive layer comprises a conductive
material selected from a group consisting of metals and
metal nitrides.

5. The semiconductor device according to claim 4,
wherein the conductive layer comprises at least one

metal selected from a group consisting of tungsten, tantalum, titanium, and aluminum.

6. The semiconductor device according to claim 4,
5 wherein the conductive layer comprises at least one metal nitride selected from a group consisting of tungsten nitride (WN), tantalum nitride (TaN), titanium nitride (TiN) and aluminum nitride (AlN).

10 7. The semiconductor device according to claim 1, wherein the conductive layer has a thickness of 100 to 2000Å.

15 8. The semiconductor device according to claim 1, wherein the metal oxide layer comprises an oxide layer having a dielectric constant of at least 3.9.

20 9. A method of fabricating a semiconductor device, comprising the steps of:

preparing a semiconductor substrate;

forming a silicon oxide layer on the semiconductor substrate;

forming a conductive layer on the silicon oxide layer; and

Concld
A1

forming a metal oxide layer at an interface between the silicon oxide layer and the conductive layer.

5 10. A method of fabricating a semiconductor device according to claim 9, wherein the step of forming a silicon oxide layer further comprises forming a silicon dioxide layer having a thickness of 10 to 100Å.

10 11. A method of fabricating a semiconductor device according to claim 9, wherein the step of forming the conductive layer further comprises forming a metal layer or a metal nitride layer.

15 12. A method of fabricating a semiconductor device according to claim 11, wherein the step of forming the metal layer further comprises forming a layer of at least one metal selected from a group consisting of tungsten (W), tantalum (Ta), titanium (Ti), and
20 aluminum (Al).

25 13. A method of fabricating a semiconductor device according to claim 11, wherein the step of forming the metal nitride layer further comprises forming a layer of at least one metal nitride selected from a group

consisting of tungsten nitride (WN), tantalum nitride (TaN), titanium nitride (TiN) and aluminum nitride (AlN).

5 14. A method of fabricating a semiconductor device according to claim 9, wherein the step of forming the conductive layer further comprises forming a conductive layer having a thickness of 100 to 2000Å.

10 15. A method of fabricating a semiconductor device according to claim 9, wherein the step of forming a metal oxide layer at an interface between the silicon oxide layer and the conductive layer further comprises a thermal treatment, the thermal treatment being
15 conducted at a temperature of 500 to 1000°C and under an inert gas ambient.

16. A method of fabricating a semiconductor device according to claim 15, wherein the inert gas comprises
20 at least one gas selected from a group consisting of nitrogen (N), argon (Ar), and helium (He).

17. A method of fabricating a semiconductor device according to claim 9, wherein the step of forming a
25 metal oxide layer further comprises forming a metal

oxide layer having a dielectric constant of at least 3.9.

18. A method of fabricating a semiconductor device
5 according to claim 9, wherein the step of forming a metal oxide layer further comprises oxidizing a portion of the metal layer with oxygen atoms from the silicon oxide layer.

10 19. A method of fabricating a semiconductor device according to claim 9, wherein the silicon oxide layer is a gate insulator and the conductive layer is a gate electrode.